

IN THE CLAIMS:

C1 ~~Claim 1, line 2, after "percent Sn" please insert --~~ wherein said alloy contains substantially no Ag or antimony --

~~Claim 7, line 1, please delete "solved".~~

~~Claim 8, line 1, please delete "solved".~~

~~Claim 9, line 1, please delete "solved".~~

~~Claim 10, line 1, please delete "solved".~~

~~Claim 11, line 1, please delete "solved".~~

~~Claim 12, line 1, please delete "solved".~~

10
C3 13. (Once amended) A lead-free solder alloy comprising 0.1 - 2 wt% Cu, 0.002 - 1 wt% Ni, 0.001-1 wt% Ge, and the remaining percent Sn [according to claim 1 wherein 0.001-1 wt% Ge is further added].

11
14. (Once amended) A lead-free solder alloy according to claim [2 wherein 0.001-1 wt% Ge is further added] 12 wherein the weight percentage of Cu falls within a range from 0.3 to 0.7 percent.

12
15. (Once amended) A lead-free solder alloy according to claim [3 wherein 0.001-1 wt% Ge is further added] 14 wherein the weight percentage of Ni falls within a range from 0.04 to 0.1 percent.

Remarks

Indication of allowable subject matter in claims 13-15 is gratefully acknowledged. Applicant has amended the application to claim priority under 35 U.S.C. § 120 as a continuation of PCT/JP99/01229, that was co-pending with the application. Applicant includes a copy of the PCT application cover sheet, the search report, a translation, the PCT claims, drawings, and description. Applicant is in the process of procuring certified copies of